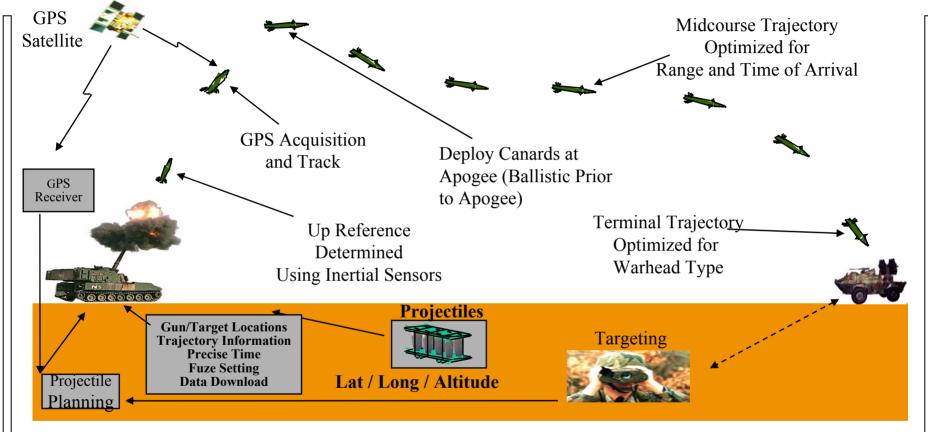


Smart Munitions and HSTSS





Working Towards Embedded Instrumentation

Briefing by: Dennis Schneider, PEO STRI (407) 384-3902

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Background

- HSTSS project was funded by OSD CTEIP, Army Sponsored and External Customers (i.e. CRADA's)
- HSTSS is a multi service instrumentation development program
- HSTSS is a low cost, micro miniature, high g (100,000 g) modular instrumentation system
- Products being delivered that allow for integration at all levels





Embedded Instrumentation Philosophy



- Design at Concept Formulation
- Choose Electronic Technology Similar to Actual Platform
- Qualify During Early Flights
- Instrumentation Evolves with Platform
- Instrumentation for DT, OT, Tactical and Training

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HSTSS Efforts

- Transmitters
- Programmable Logic Devices / Pulse Code Modulation Encoders
- Packaging
- Batteries
- •Sensors

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Today's and Next Generation Transfer **Transmitters**





Non PLL Transmitter (15 mm, ARL Design)

Transmitter Architecture

- •Programmable, multimode and multiband
- •Efficient Complex Amplitude and Phase modulation
- •Digital interface and control

Much Lower Cost and Reusable building blocks

•Two chip solution cost and size benefit

Integrated transmitter, processor, and antenna solution Modulation-independent transmitter solutions

- •FM, GMSK, QPSK, HPSK, OFDM
- •10kbps to 10Mbps
- •L & S and ISM Bands



0.5 mW Transmitter $(28.6 \, \text{mm})$



1 Watt FIU Transmitter $(1.75 \times 3 \text{ Inch})$



0.25 mW Transmitter $(28.6 \, \text{mm})$



1 W or 2 W Support Board $(28.6 \, \text{mm})$

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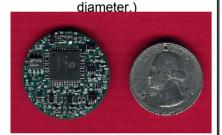
PLD Encoders

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The HSTSS IPT has developed several g-hardened encoding and signal processing devices utilizing various programmable technologies, including Field Programmable Gate Array Complex Programmable Logic Device (CPLD), and PICmicro controller technologies. Designs are configurable for analog channel count, bits/word, update rate, and accommodation of digital inputs. Signal delay is currently being incorporated into an encoder board design.

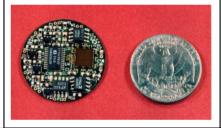
PICmicro based PCM Encoder module (1.125" (28mm)



FPGA PCM Encoder Board Measures 2" X 4"



FPGA based PCM Encoder (1.125" (28mm) diameter.)

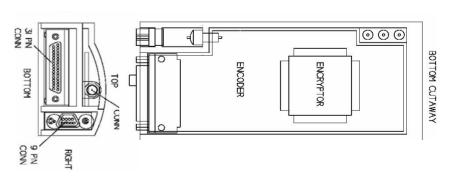


CPLDbased PCM Encoder (0.75" (15mm) diameter.)



Systems with Utilizing HSTSS Technologies





Excalibur Program

ERGM Program

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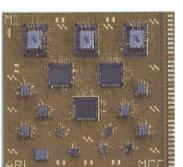


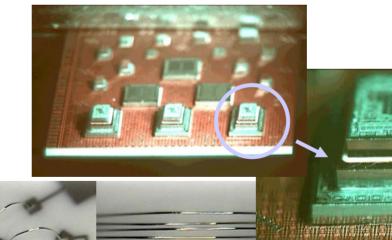
Advanced High-g Packaging



- Establish & qualify microelectronic assembly techniques for ballistic environment
 - Establish boundaries
 - Adopt & modify commercial techniques
 - Address substrate materials, adhesives, interconnect, etc.











Air-gun pre-qualification tests with HSTSS batteries





Ultralife Lithium Ion NF Cells
Nominal Voltage: 4V
Cell Dimensions: 0.99" x 0.99" x 0.195"
Typical Discharge Current: 250 mA



Ultralife Li/MnO₂ NF Cells NF1 - single cell NF3 - 3-cell battery Nominal Voltage: 24V

Cell Dimensions: 0.98" x 0.98" x 0.14" Typical Discharge Current: 250mA

 Ultralife Lithium Ion and Li/MnO₂ tested at 50, 80, and 100 kg's (nom.)

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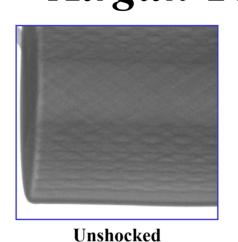


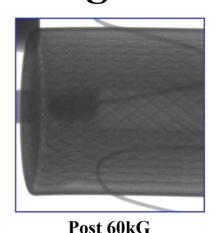
Li/MnO₂ Cylindrical Cells
Airgun Testing

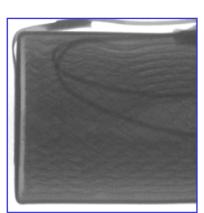












Post 100kG

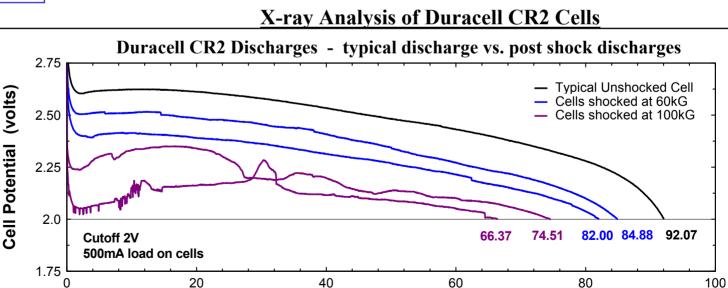
Typical
Duracell CR2

Airgun Test Summary

vertical orientation

2 cells at 60kG no failures

4 cells at 100kG 1 failure



Time (minutes)

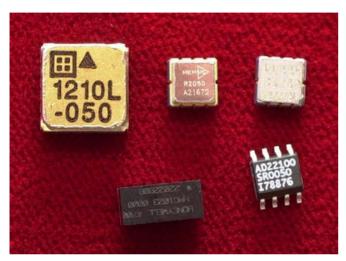
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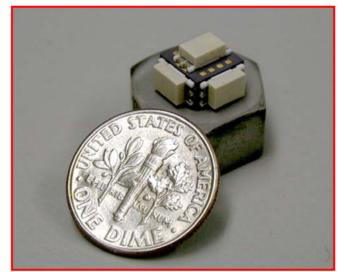
High G Sensors Endevco Model 73

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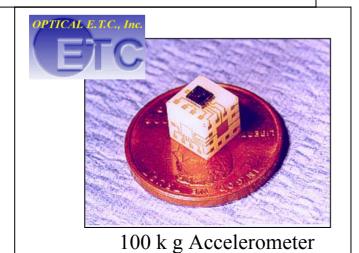




High-G Survivable, Low-Cost, MEMS and other miniature COTS Parts.



60 k g Accelerometer





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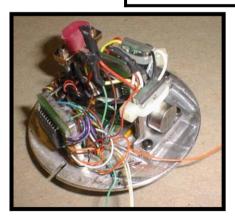


T&E/S&T El Projects



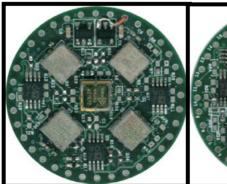
- MEMS Based Instrumentation for Flight Testing of Advanced Munitions
 - Leverage ARL's HSTSS telemetry experiences
 - Uses custom MEMS sensors: angular rate, accelerometer, & magnetometer
 - Saves time/\$ in assembly/calibration may only use 2-3 multi-axis/multi-sensor chips

Sensor Suite Type	Volume (in ³)	Power (m-watts)
2.75" Stinger Kit	3.70	800
HSTSS Board	0.30	160
Next Generation	0.03	80



Stinger Sensor Kit ~ 1998

- 4 MEMS accelerometers
- 2-axis GMR magnetometer
- 2 non-MEMS rate sensors





HSTSS Board (bottom/top) ~ 2002

- 3-axis GMR magnetometer
- 4 MEMS accelerometers
- 4 MEMS accelerometers for "spin"
- Temperature sensor for calibration

Multi-Axis Multi-Instrument In-Plane Out-of-Plane Single/Dual Chip

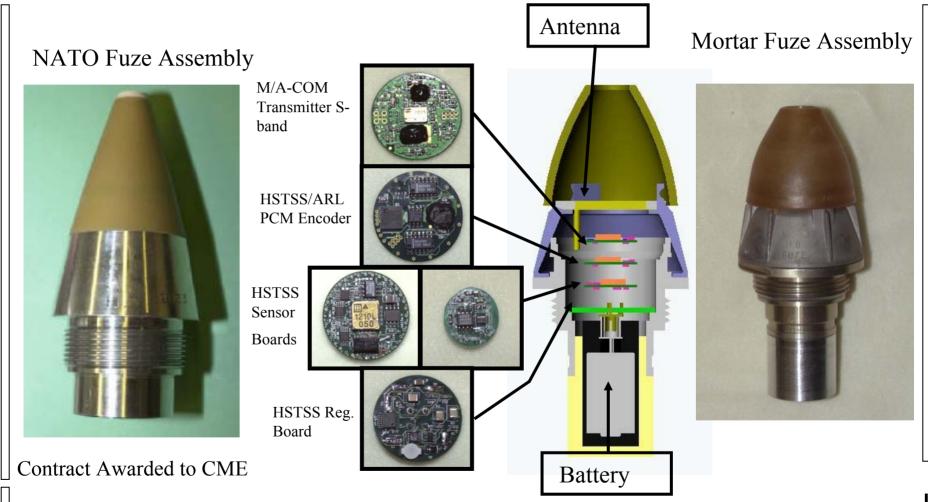
Notional Next Generation Need

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HSTSS Telemetry Assembly





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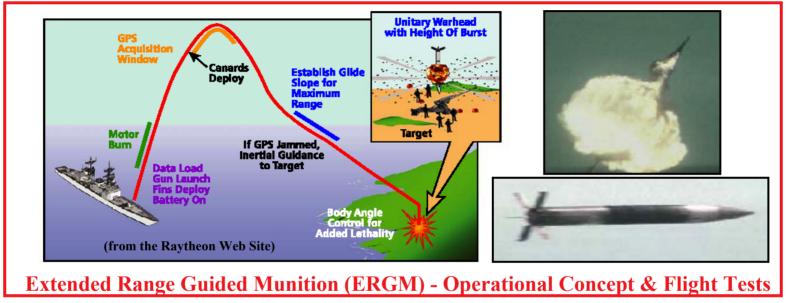




Embedded Instrumentation for Projectiles Fielded HSTSS







- ERGM/PMS-529, Raytheon, and CTEIP's Hardened Subminiature Telemetry & Sensor (HSTSS) Program have teamed to introduce a "non-intrusive" telemetry module
- Estimated cost avoidance due to the reduction of an additional 40 OPEVAL Rounds to ERGM ~ \$2.8M
- Fewer projectiles needed with a single "test/tactical design" concept
- Estimated total cost savings/avoidance ~ \$13M

So don't worry - even difficult El is here

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Conclusion



• Technologies are available employ embedded concepts

• Include instrumentation as a <u>subsystem</u> during concept formulation

• Identify a roadmap on what the instrumentation will be required to do, i.e. lifecycle support needs to be defined

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